								F	REVIS	IONS										
LTR					D	ESCF	RIPTIC	N					D	ATE (Y	/R-MO-I	DA)		APPF	ROVED)
L	Incorporated NOR's 5962-R110-94 and 5962-R013-to table I for device type 07. Redraw entire documer												K.A. Cottongim							
REV SHEET																				
SHEET	L	L	L	L	L															
SHEET	L 15	L 16	L 17	L 18	L 19															
SHEET REV SHEET REV STATU	15 JS				19		L	L	L	L	L	L	L	L	L	L	L	L	L	L
SHEET REV SHEET REV STATU	15 JS			18	19 /		L 1	L 2	L 3	L 4	L 5	L 6	L 7	L 8	L 9	L 10	L 11	L 12	L 13	L 14
SHEET REV SHEET REV STATU OF SHEETS	15 JS			18 RE\ SHE	19 /		1				5	6	7 SE EL	8 ECTR	9 ONICS	10 S SUP	11		13	
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A STA MICRO	JS S S NDA	16 RD CUIT	17	18 RE\ SHE PREI Dona	19 / EET	sborne BY	1				5	6	7 SE EL	8 ECTR	9	10 S SUP	11	12	13	
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A STA MICRO DRA THIS DRAWI FOR U	JS S S S S S S S S S S S S S S S S S S	RD CUITIG	17	18 RE\ SHE PREI Dona CHE D. A	19 / EET PARED	BY zo BY	1			4 MIC	5 DI	6 EFENS	7 SE ELL DA	8 ECTR	9 ONICS	10 S SUP O 454	11 PLY 0	12	13 R	14
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A STA MICRO DRA THIS DRAWI FOR U	JS S S S S S S S S S S S S S S S S S S	RD CUITIG VAILABALL ITS DF THE	17 F	18 REN SHE PREI Dona CHEI D. A APPI N. A	19 / EET PARED Ild R. O CKED I . Dicen	BY zo BY APPR(1	2		4 MIC	5 DI ROCI	6 EFENS IRCUI	7 SE ELL DA	8 ECTR YTON BRID	9 ONICS	10 S SUP O 454 TAL,	PLY C	12 CENTE	13	14
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A STA MICRO DRA THIS DRAW! FOR U DEPA AND AGE	JS S S NDA OCIR AWIN ING IS A USE BY A ARTMEN ENCIES (RD CUITIG VAILABALL ITS DF THE	17 F	18 RE\ SHE PREI Dona CHE D. A APPI N. A DRA	19 / EET PARED Idd R. O CKED I . Dicen ROVED . Hauck	BY zo DBY K APPR(87-0	1 DVAL E 08-06	2		MIC VOL	5 DI ROCI	6 RCUI	7 DA T, HY	8 ECTR YTON BRID EIVER	9 ONICS	10 S SUP O 454 TAL,	PLY C	12 CENTE	13	14

- 1. SCOPE
- 1.1 <u>Scope</u>. This drawing describes device requirements for class H hybrid microcircuits to be processed in accordance with MIL-PRF-38534.
 - 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device types	Generic number	Circuit function 1/
01	BUS-63125, BUS-63126	Dual channel, driver-receiver
02	BUS-63125II, BUS-63126II	Low power, dual channel, driver-receiver
03	ARX2411	Dual channel, driver-receiver
04	ARX3411	Low power, dual channel, driver-receiver
05	NHI-1500	Low power, dual channel, driver-receiver
06	FC1553623	Low power, dual channel, driver-receiver 2/
		with thermal protection
07	CT1487D	Low power, dual channel, driver-receiver
08	MR63125M	Low power, dual channel, driver-receiver
09	FC1553621	Low power, dual channel, driver-receiver

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
U	See figure 1	28	Dual-in-line
Χ	See figure 1	36	Dual-in-line
Υ	See figure 1	36	Flat package
Z	See figure 1	28	Flat package

1.2.3 <u>Lead finish</u>. The lead finish shall be as specified in MIL-PRF-38534. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

^{2/} For device type 06 only, the the thermal protection operation is as follows: With the thermal overide pins 4 and 13 disconnected transmission amplitude decreases as case temperature exceeds approximately 175° C and is restored as case temperature decreases. With pins 4 and 13 connected to 0 volts this feature is effectively disabled.

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 $[\]underline{1}/$ Interfaces with Manchester encoder-decoder described in DESC drawing 78029.

1.3 Absolute maximum ratings. Supply voltage range: V_{CC} (devices 01, 03, 04, 05, 07, and 08)------0.3 V dc to +18 V dc 40 V_{P-P} Receiver common mode voltage range - - - - - - - --10 V dc to +10 V dc 200 mA Power dissipation (P_D) at T_C = +125° C: (devices 01 and 08)----- (device 02) 4 W 3 W (device 03) -----3.3 W 1/ (device 04) -----2 W 1/ (device 05) -----0.96 W 1/ (devices 06 and 09)-----1.65 W <u>1</u>/ (device 07) -----3 W Storage temperature range -65°C to +150°C Lead temperature (soldering, 10 seconds)------+300°C Junction temperature (T_J): (devices 01-04, 06, 07, 08, and 09)-----+160°C (device 05) ------+150°C Thermal resistance, junction-to-case (Θ_{JC}): (devices 01 and 05) ----- (devices 02 and 08) -----8.8° C/W 7.0° C/W (device 03) -----47.2° C/W (device 04) ------88° C/W (devices 06 and 09) ------ 18° C/W (device 07) -----60° C/W Thermal resistance, junction-to-ambient (Θ_{IA}): (devices 01 and 05) ------ (devices 02 and 08) ------28.8° C/W (device 03) -----67.2° C/W (device 04) ----- 108° C/W (devices 06 and 09)-----35° C/W 80° C/W 1.4 Recommended operating conditions. Supply voltage range: Receiver differential voltage: (devices 01, 02, 03, 06, and 09) ----- 30 V_{P-P} (devices 04, 05, 07, and 08) - - - - 40 V_{P-P} Receiver common mode voltage range: (devices 01, 02, 03, 04, 06, and 09) ----- -5 V dc to +5 V dc

1/ One channel transmitting at 100 percent duty cycle and the second channel at standby.

Driver peak output current (all devices) - - - - - - - 180 mA

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1.0 MHz maximum

1.4 Recommended operating conditions - continued.

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbook</u>. Unless otherwise specified, the following specification, standards, and handbook of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

PERFORMANCE

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.
MIL-STD-973 - Configuration Management.

MIL-STD-1835 - Microcircuit Case Outlines.

HANDBOOK

MILITARY

MIL-HDBK-1553 - Multiplex Application Handbook.

(Copies of the specification, standards, and handbook required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38534 and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 and figure 1 herein.
- 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 2.
- 3.2.3 Timing waveforms. Timing waveforms shall be as specified on figure 3.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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		171	BLE I. <u>Electrical performano</u>		<u></u>	1		
Test	Symbol		Conditions 1/	Device	Group A subgroups	Limits		Unit
			-55° C ≤ T _C ≤ +125° C unless otherwise specified	types		Min	Max	
Receiver	Input level	V _I	Differential input, pin 15 to pin 16 2/	All	4, 5, 6	40		V _{P-P}
	Input common mode voltage range	V _{ICM}	Independent of xfmr or in accordance 2/ with MIL-HDBC-1553	01,02,03, 04,06,09	4, 5, 6	-5	+5	V(pk)
			section 5.1.2.2	05,07,08		-10	+10	
	Output low voltage	V _{OL}	I _{OL} = 16 mA	01, 02	1, 2, 3		0.5	V
			I _{OL} = 4 mA	03,04,07, 08	_		0.5	
			I _{OL} = 8 mA	05,06,09			0.5	
	Output high voltage	V _{OH}	I _{OH} = -0.4 mA	All	1, 2, 3	2.5		V
Transmitter	Input low voltage	V _{IL}	<u>3</u> /	All	1, 2, 3		0.7	V
	Input high voltage	V _{IH}	<u>3</u> /	All	1, 2, 3	2		V
	Input low current	I _{IL}	V _{IL} = 0.4 V	01,06,09	1, 2, 3	-1.6		mA
				02		-0.72		
				00		2.0		
				03		-3.2		=
				04,05,08	+	-0.4		-
				07		-1.0		
	Input high current	I _{IH}	V _{IH} = 2.7 V	All	1, 2, 3		0.04	mA
	Output voltage	v _o	Across 35Ω load	All	1, 2, 3	6	9	V _{P-P}

See footnotes at end of table.

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	-	TABLE I. <u>EI</u>	ectrical performance chara	acteristics - C	Continued.			
	Test	Symbol	Conditions 1/	Device	Group A	Lim	its	Unit
			-55° C ≤ T _C ≤ +125° C unless otherwise specified	types	subgroups	Min	Max	
Transmitter	Output noise voltage	V _{ON}	Across 35Ω load	All	4, 5, 6		10	mV _{p-p}
Receiver strobe	Input low voltage	V _{SIL}	<u>3</u> /	01-03, 05-09	1, 2, 3		0.7	V
				04			0.4	
	Input high voltage	V _{SIH}	<u>3</u> /	All	1, 2, 3	2		V
	Input low current	I _{SIL}	V _{SIL} = 0.4 V	01,06,09	1, 2, 3	-1.6		mA
				02,05	_	-0.72		<u> </u>
				03	_	-0.8		+
				04,08	<u> </u>	-0.4		<u> </u>
				07		-1.0		
	Input high current	I _{SIH}	V _{SIH} = 2.7 V	All	1, 2, 3		0.04	mA
Transmitter inhibit	Input low voltage	V _{IIL}	<u>3</u> /	All	1, 2, 3		0.7	V
	Input high voltage	V _{IIH}	<u>3</u> /	All	1, 2, 3	2		V
	Input low current	I _{IIL}	V _{SIL} = 0.4 V	01,03, 06,09	1, 2, 3	-1.6		mA
				02		-0.72		
				04,05,08	+	-0.4		+

V_{SIH} = 2.7 V

I_{IIH}

See footnotes at end of table.

Input high current

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07

ΑII

-1.0

0.04

 $\mathsf{m}\mathsf{A}$

1, 2, 3

	Test	Symbol	Conditions 1/	Device	Group A subgroups	Lim	nits	Unit
			-55° C ≤ T _C ≤ +125° C unless otherwise specified	types	subgroups	Min	Max	
Power supply	Total current	I _{CC} -SB	(standby mode)	01 03,08 04 05 07	1, 2, 3		55 32 1 25 44	mA
		I _{EE} -SB		07 01,08 06,09 02 03 04			55 30 35 26 16.5	
		I _{CC1} -SB		07 01,06,09 02 03 04 05,08			70 35 45 20 30 25	
		I _{CC} -25	(25% duty cycle into 35Ω load	01,04,08 03 05	4, 5, 6		55 90 69	
		I _{EE} -25		07 01,06,08 09 02 <u>2</u> / 03 04			100 100 100 80 26 21	
		I _{CC1} -25		07 01 02 <u>2</u> / 06,09 03 04 05,08			70 35 45 45 20 30 25 90	
		I _{CC} -50	(50% duty cycle into 35Ω load)	01,08 03 04 05	4, 5, 6		55 140 110 118	
		I _{EE} -50		07 01 08 02,06,09 03 04			155 145 150 130 26 25	

See footnotes at end of table

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	Test	Symbol	Conditions 1/	Device	Group A	Lin	<u>nits</u>	Unit
			-55° C ≤ T _C ≤ +125° C unless otherwise specified	types	subgroups	Min	Max	
Power supply	Total current	I _{CC1} -50	(50 % duty cycle into 35Ω load)	01 02,06,09 03 04 05,08 07			35 45 20 30 25 90	
	Total current	I _{CC} -100	(100% duty cycle into 35Ω load)	01,08 03 04 05	1, 2, 3		55 240 220 209 260	mA
		I _{EE} -100		01 02 <u>2</u> / 06,08,09 03 04 07			255 255 255 26 30 70	
		I _{CC1} -100		01 <u>3/</u> 02 <u>2/</u> 03,08 04 05 06,09 07			35 45 20 30 25 55 90	
Receiver	Input resistance	R _{IN}	1 MHz sine wave 2/	All	4, 5, 6	7		kΩ
	Input capacitance	C _{IN}	1 MHz sine wave <u>2/</u> T _C = +25° C	All	4		5	pF
	Threshold voltage	V_{TH}	<u>4</u> /	08	1, 2, 3	0.56	1.1	V _{P-F}
				01,02, 03,04, 05		0.56	1.0	
				06,09	_	0.6	1.2	+
				07		0.86	1.1	
		V_{TH}	Group C end-point 4/ electricals	All	1, 2, 3	0.50	1.1	V _{P-P}

See footnotes at end of table.

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	Test	Symbol	Conditions 1/	Device	Group A	Li	mits	Unit
			-55° C ≤ T _C ≤ +125° C unless otherwise specified	types	subgroups	Min	Max	
Transmitter	Output resistance (transmitter off)	R _{OUT}	1 MHz sine wave 2/	All	4, 5, 6	10		kΩ
	Output capacitance (transmitter off)	C _{OUT}	1 MHz sine wave <u>2/</u> T _C = +25° C	All	4		5	pF
	Output offset voltage	V _{OS}	2/ 5/	All	4, 5, 6	-90	+90	mV(pk)
	Peak amplitude variation	A _V	<u>6</u> /	All	4, 5, 6	-15	+15	%
Receiver	Delay time, input to output	t _{DR}	Delay time from dif- 2/ ferential input zero <u>crossi</u> ng to DATA or DATA (see figure 3)	All	9,10,11		400	ns
	Strobe delay	t _{DS}	Delay time from strobe rising or	01,02,03,05, 06,07,08,09	9,10,11		200	
			fall <u>ing edg</u> e to DATA or DATA (See figure 3) <u>2</u> /	04			250	
Transmitter	Rise time	t _R	Output load = 35Ω (See figure 3)	All	9,10,11	100	300	_
	Fall time	t _F		All	9,10,11	100	300	
	Delay time	t _{DT}	(See figure 3) <u>2</u> /	01,02,03, 05,06,09	9,10,11		250	_
				04,08	<u> </u>		350	_
				07			200	_
	Inhibit delay inhibiting	t _{DI-H}	(See figure 3) <u>2</u> /	All	9,10,11		450	

See footnotes at end of table.

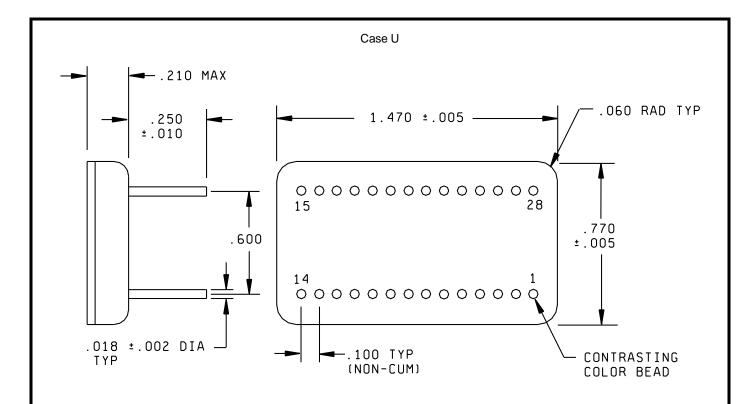
STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87579
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TABLE I. Electrical performance characteristics - Continued.
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	Test	Symbol	Conditions 1/	Device	Group A	Lir	mits	Unit
			-55° C ≤ T _C ≤ +125° C unless otherwise specified	types	subgroups	Min	Max	
Transmitter	Inhibit delay active	t _{DI-L}	(See figure 3) <u>2</u> /	01,02,03, 04,05,08	9,10,11		250	_
				06,09	+		300	-
				07			150	

- $\underline{1}/V_{CC}$ = 15 V, V_{EE} = -15 V, V_{CC1} = +5 V. All specifications and limits are for a single channel with no connections made to the other channel.
- 2/ This parameter is tested initially and after any process or design change which might affect this parameter.
- 3/ These parameters are tested on a go-no-go basis in conjuction with other measured parameters and are not directly testable.
- 4/ Threshold is measured in direct coupled mode including the transformer. Threshold is the maximum level on the BUS at which there are no pulses on either receiver output. Divide by 1.4 to obtain threshold in transformer coupled mode. Add 0.14 V in direct coupled mode or 0.10 V in transformer coupled mode to obtain threshold at which no errors are observed when receiver is used with 15530 CMOS Manchester encoder-decoder.
- 5/ Measured across 35Ω load, 2.5 µs after parity bit mid-bit zero crossing of a 660 µs message.
- $\underline{6}$ / Measured across 35 Ω load, variation of average peak amplitude.

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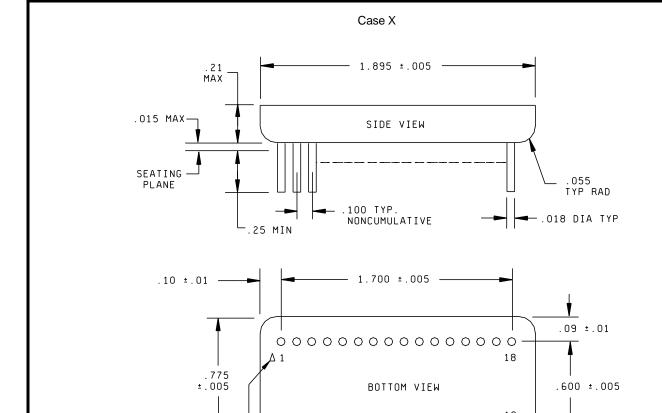


Inches	mm
.002	0.05
.005	0.13
.010	0.25
.018	0.46
.060	1.52
.100	2.54
.210	5.33
.250	6.35
.600	15.24
.770	19.56
1.470	37.34

- 1. Dimensions are in inches.
- 2. Metric equivalents are given for general information only.
- 3. Lead indentification numbers are for reference only.
- 4. Lead spacing dimensions apply only at seating plane.

FIGURE 1. Case outlines.

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PIN 1

INDENTIFIER

Inches	
mm	
.005	0.13
.01	0.3
.015	0.38
.018	0.46
.055	1.40
.086	2.18
.09	2.3
.10	2.5

.100 2.54 .600 15.24 .775 19.68 1.700 43.18 1.895 48.13

NOTES:

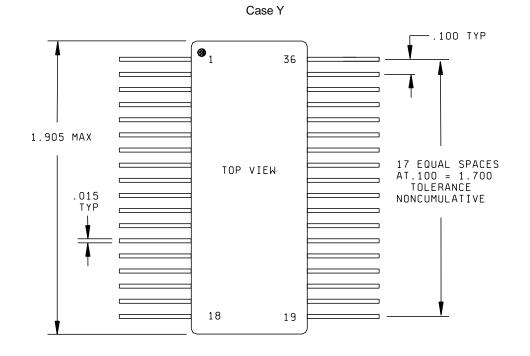
- 1. Dimensions are in inches.
- 2. Metric equivalents are given for general information only.
- 3. Lead identification numbers are for reference only.
- 4. Lead spacing dimensions apply only at seating plane.

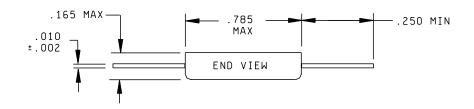
FIGURE 1. Case outlines - Continued.

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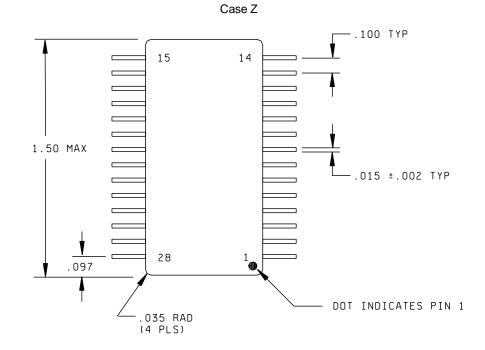


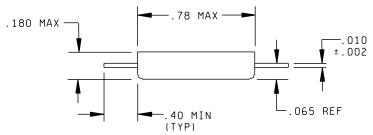
Inches	mm	
.002	0.05	
.010	0.25	
.015	0.38	
.100	2.54	
.165	4.19	
.250	6.35	
.785	19.94	
1.700	43.18	
1.905	48.39	

- 1. Dimensions are in inches.
- 2. Metric equivalents are given for general information only.
- 3. Lead indentification numbers are for reference only.
- 4. Lead spacing dimensions apply only at seating plane.

FIGURE 1. Case outlines - Continued.

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Inches	mm
.002	0.05
.003	0.08
.010	0.25
.015	0.38
.035	0.89
.065	1.65
.097	2.46
.100	2.54
.180	4.51
.40	10.16
.78	19.81
1.50	38.10

- 1. Dimensions are in inches.
- 2. Metric equivalents are given for general information only.
- 3. Lead identification numbers are for reference only.
- 4. Lead spacing dimensions apply only at seating plane.

FIGURE 1. Case outlines - Continued.

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Cases X and Y

Pin	Function	Channel
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30	Function TX data out TX data out Gnd NC RX data out Strobe Gnd RX data out Gnd TX data out Gnd TX data out Gnd NC RX data out TX data out Cnd NC RX data out Strobe Gnd NC RX data out Strobe Gnd RX data in RX data in RX data in TX data in TX data in TX data in TX data in RX data in	Channel One One One One One One One Two
31 32 33 34 35 36	Gnd VEE VCC1 Inhibit TX data in TX data in	One One One One One One

- 1. GND pins should all be connected externally. Pins 19 and 28 are +15 V dc for device types 01, 03, 04, 05, and 07 only, no connect (NC) for device types 02, 06, and 09.
- 2. Pins 4 and 13 are available for the thermal protection for device type 06.

FIGURE 2. Terminal connections.

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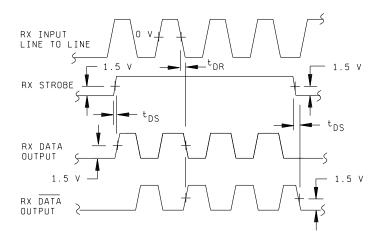
Cases U and Z

1 TX <u>data</u> out/RX <u>data</u> in One 2 TX data out/RX data in One 3 Gnd One 4 RX <u>stro</u> be One 5 RX data out One	Pin	Function	Channel
7 Case TX data out/RX data in Two 9 TX data out/RX data in Two 10 Gnd Two 11 RX strobe Two 12 RX data out Two 13 RX data out Two 14 No connection Two 15 Gnd Two 16 VEE Two 17 VCC1 Two 18 TX inhibit Two 19 TX data in Two 20 TX data in Two 21 VCC Two 22 Gnd One 23 VEE One 24 VCC1 One 25 Inhibit One 26 TX data in One 27 TX data in One 28 VCC One	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27	TX data out/RX data in Gnd RX strobe RX data out RX data out Case TX data out/RX data in TX data out/RX data in TX data out/RX data in Gnd RX strobe RX data out RX data out No connection Gnd VEE VCC1 TX inhibit TX data in TX data in VCC Gnd VEE VCC1 Inhibit TX data in	One One One One One Two

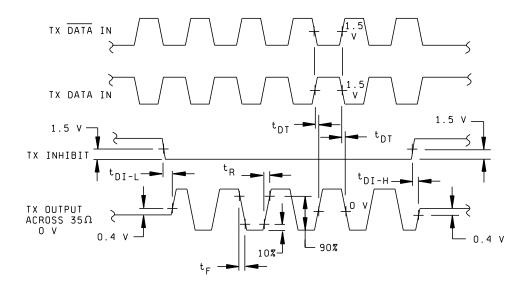
NOTE: GND pins should all be connected externally.

FIGURE 2. <u>Terminal connections</u> - Continued.

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Receiver timing



Transmitter timing

FIGURE 3. Timing waveforms.

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- 3.5 Marking. Marking shall be in accordance with MIL-PRF-38534. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in QML-38534 (see 6.6 herein).
- 3.6 <u>Manufacturer eligibility</u>. In addition to the general requirements of MIL-PRF-38534, the manufacturer of the part described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, produced on the certified line, for each device type listed herein. The data should also include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DESC-EL) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in QML-38534 (see 6.6 herein). The certificate of compliance submitted to DESC-EL prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38534 and the requirements herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.
- 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534.
- 4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DESC-EL or the acquiring activity upon request. Also, the test circuit shall specifiy the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I in test method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-PRF-38534 and as specified herein.
- 4.3.1 Group A inspection. Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7 and 8 shall be omitted.
- 4.3.2 Group B inspection. Group B inspection shall be in accordance with MIL-PRF-38534.
- 4.3.3 Group C inspection. Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DESC-EL or the acquiring activity upon request. Also, the test circuit shall specifiy the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1005 of MIL-STD-883.

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- Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.3.4 Group D inspection. Group D inspection shall be in accordance with MIL-PRF-38534.

TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534 group A test table)
Interim electrical parameters	
Final electrical test parameters	1*,2,3,4,5,6,9,10,11
Group A test requirements	1,2,3,4,5,6,9,10,11
Group C end-point electrical parameters	1,2,3

^{*} PDA applies to subgroup 1.

- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for original equipment design applications and logistic support of existing equipment.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EL, telephone (513) 296-6047.
- 6.5 Comments. Comments on this drawing should be directed to DESC-EL, Dayton, Ohio 45444, or telephone (513) 296-5373.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in QML-38534. Additional sources will be added to QML-38534 as they become available. The vendors listed in QML-38534 have agreed to this drawing and a certificate of compliance (see 3.7 herein) has been submitted to and accepted by DESC-EL.

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